

<b>Notice of References Cited</b>		Application/Control No.	Applicant(s)/Patent Under Reexamination NOGAMI ET AL.	
		Examiner Thomas J. Magee	Art Unit 2811	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-5,695,810	12-1997	Valery M. Dubin et al.	427/96
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	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

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**NON-PATENT DOCUMENTS**

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	V	Y. Shacham-Diamand and S.Y. Lopatin, "High Aspect Ratio Quarter-Micron Electroless Copper Integrated Technology," Proc. Materials for Advanced Metallization (Europe) (1997), pp. 11 - 14.
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.